



Ultra-thin optical isolator :

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The ultra-thin optical isolator is developed in response to the needs of customers for short focal length products and market cost reduction. The thickness of the product with a metal ring is only 0.75mm, and the thickness of the bare chip product is only 0.5mm, and the bare chip product has no risk of degaussing reliability .

Main features :

- Ultra-low insertion loss
- Ultra high temperature stability
- low cost design
- smaller package size

Typical application:

- TOSA / BOSA / BIDI
- Butterfly package laser

Product parameters :

parameter		unit	Specification
Center wavelength (λ_c)		nm	18 CWDM wavelengths
bandwidth		nm	± 20
Isolation ($@\lambda_c$ & 25°C)	Min	dB	30
Isolation (@ full bandwidth, full temperature)	Min	dB	25
Insertion loss (full temperature range)	Max	dB	0.3
Core size		mm	0.5, 0.6, 0.7, 0.8, customized
withstand power	Max	mW	300
Centerpiece Placement Angle	Typical	°	7 ± 1
Operating temperature		°C	-40 to +85
storage temperature		°C	-40 to +85
size		mm	$\Phi 2.5 \times 0.75$ mm, (with metal ring, maximum CA1.3mm) $\Phi 1.8 \times 0.75$ mm, (with metal ring, maximum CA0.85mm) $\Phi 1.25 \times 0.75$ mm, (with metal ring, CA0.5mm) Thickness < 0.5mm (bare chip)
Incident polarization direction error		°	± 10
RoHS			RoHS Compliant